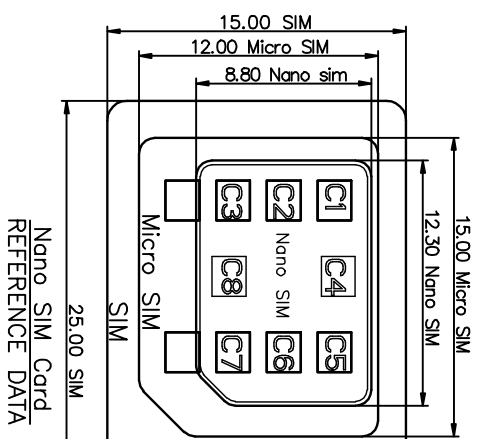
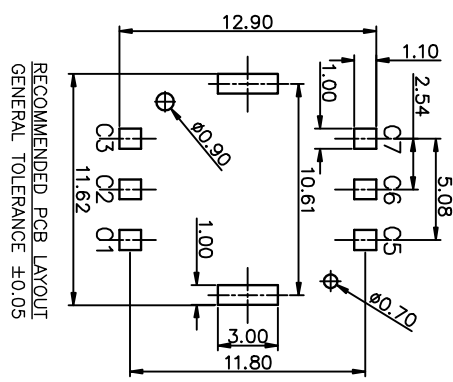
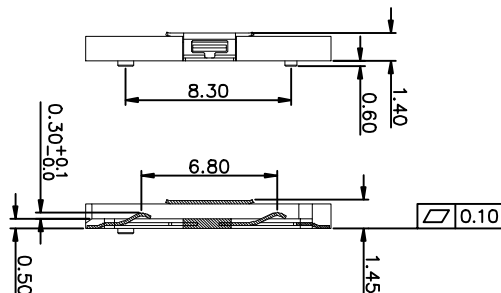
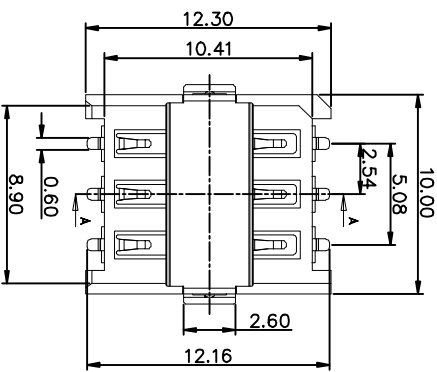
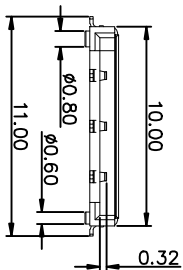
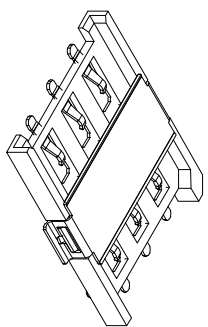
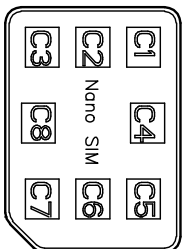


REV.	EQN.NO.	MODIFY CONTENT	DATE
A		NEW	2014/12/29



- C1 ---> VCC
- C2 ---> RST
- C3 ---> CLK
- C5 ---> GND
- C6 ---> VPP
- C7 ---> I/O



- Notes:
- Material:
    - Housing: LCP 30%GF, UL94V-0, Black
    - Contact : Phosphor Bronze, T=0.15mm
    - Shell: SUS304-H, T=0.15mm
  - Plating:
    - Contact Area: 3U" GOLD PLATED
    - Solder Area: G/F Gold
    - Underplating: Ni overall 50u" Min.
  - Shell:
    - Solder Area: G/F Gold
    - Underplating: Ni overall 50u" Min.
  - Mechanical:
    - Life cycles: 5000.
  - Electrical:
    - Voltage Rating: 30V AC RMS
    - Current Rating: 0.5A AC RMS Max
    - Operating Temperature: -20°C to +80°C
    - Dielectric Withstanding Voltage: 100V AC (60Sec Min)
    - Insulation Resistance: 100MΩ Min
    - Contact Resistance: 30mΩ Max

DESCRIPTION OF PLATING ON TERMINALS		NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

GENERAL TOLERANCE		DWG NO.	Scale	1:1
X±0.45	x'±5"		UNIT	mm
X±0.35	.x'±2"			
.XX±0.25	.xx±1"	Part NO.		
.XXX±0.15	.xxx±0.5"			
		DR:		
		Date	2014/12/29	

深圳市迈瑞康电子有限公司